

In the Specification:

Page 4, second paragraph:

A1
These objects, and others, which will be made more apparent hereinafter, are attained in a layer sequence built on a substrate in thin-film technology, said layer sequence comprising an electrically conductive sputtered layer, which is reinforced by a similar electrically conductive reinforcing layer, which is applied to the electrically conductive sputtered layer by another method, and at least one electronic component.

Page 4, last paragraph, running to page 5:

A2
In a conventional layer sequence in thin-film technology according to figure 1 an adherent sputtered layer 2 having a thickness of a few tens of nanometers is provided first on a substrate 1. Then a sputtered resistor layer 3 with a thickness of the same order of magnitude as the first sputtered adherent layer 2 is applied over it. Then similarly a gold sputtered layer 4 having a thickness in a range between about 200 nm and 400 nm is applied over the sputtered resistor layer 3. Finally an additional gold reinforcing layer 5, which was produced by galvanic deposition, chemical reinforcement or physically (for example by rolling on or spraying), having a thickness of about 2 to 10 micrometers was provided on the gold sputtered layer 4.

Page 8, third full paragraph (beginning about line 12):